

Listing of the Claims:

- 1-12. (canceled)
13. (original) A semiconductor assembly comprising:
a IC having a plurality of metallic sockets arrayed on a mounting surface;
a PCB having a plurality of metallic projections arrayed on a mounting surface;
wherein the PCB and IC are positioned so that a plurality of the sockets adjoin a plurality of the projections; and
a plurality of solder joints coupling the IC sockets adjoining the PCB projections.
14. (original) A semiconductor assembly according to claim 13 wherein the solder joints are detachable.
15. (original) A semiconductor assembly according to claim 13 wherein the solder joints comprise low melting point solder.
16. (original) A semiconductor assembly according to claim 13 wherein the projections on the mounting surface of the PCB further comprise high melting point solder.
17. (original) A semiconductor assembly according to claim 13 wherein the projections on the mounting surface of the PCB further comprise metallic nodes affixed to selected locations on the PCB.
18. (original) A semiconductor assembly according to claim 13 wherein the projections on the mounting surface of the PCB further comprise metallic nodes affixed to selected locations on the PCB by high melting point solder.

19. (original) A BGA assembly comprising:
 - a IC having a plurality of metallic sockets arrayed on a mounting surface;
 - a PCB having a plurality of metallic projections arrayed on a mounting surface;
wherein the PCB and IC are positioned so that a plurality of the sockets adjoin a plurality of the projections; and
 - a plurality of solder joints coupling the IC sockets adjoining the PCB projections.
20. (original) A BGA assembly according to claim 19 wherein the solder joints are detachable.
21. (original) A BGA assembly according to claim 19 wherein the solder joints comprise low melting point solder.
22. A BGA assembly according to claim 19 wherein the projections on the mounting surface of the PCB further comprise high melting point solder.
23. (original) A BGA assembly according to claim 19 wherein the projections on the mounting surface of the PCB further comprise metallic nodes affixed to selected locations on the PCB.
24. (original) A BGA assembly according to claim 19 wherein the projections on the mounting surface of the PCB further comprise metallic nodes affixed to selected locations on the PCB by high melting point solder.